CALL FOR PAPERS

2020 IEEE WORLD CONGRESS ON SERVICES
CLOUD/ICWS/SCC/SMDS/DHAASS

✱ NEW DATE: July 20-24, 2020   BEIJING, CHINA

http://conferences.computer.org/services/2020/

IEEE · IEEE COMPUTER SOCIETY · 中国计算机学会 CCF TCSC · PEKING UNIVERSITY 北京大学 · IBM Research

The safety and well-being of all conference participants is our priority. We will continue to monitor official travel advisories related to the Corona Virus and update the event website to keep you informed. We encourage you to review the conference's "Travel and Safety Information" page for tips and travel recommendations provided by IEEE. **The current plan is that 2020 IEEE World Congress on Services will still be held in Beijing with the following new set of key dates:**

Normal paper submission due: **March 5, 2020 (5:00 am, UTC)**
Final notification to authors: **April 20, 2020**
Camera ready manuscripts due: **May 4, 2020**
Congress dates: **July 20-24, 2020**

Send inquiries to: **ieeecs.services@gmail.com**
For more information, see:
http://conferences.computer.org/services/2020/

The 2020 IEEE World Congress on Services (SERVICES) will be held on July 20-24, 2020 in Beijing, China. The Congress is solely sponsored by the IEEE Computer Society under the auspice of the Technical Committee on Services Computing (TCSVC). The scope of the Congress will cover all aspects of services computing and applications, current or emerging. It covers various systems and networking research pertaining to cloud, edge and Internet-of-Things (IoT), as well as technologies for intelligent computing, learning, big data and blockchain applications, while addressing critical issues such as high performance, security, privacy, dependability, trustworthiness, and cost-effectiveness. The Congress will also include symposia and workshops supporting deep-dive discussions on emerging important topics, and complement the Congress program with industry and application presentations and panels. Authors are invited to prepare early and submit original papers to any of these conferences at www.easychair.org. All submitted manuscripts will be peer-reviewed by at least 3 reviewers. Accepted and presented papers will appear in the conference proceedings published by the IEEE Computer Society Press. The Congress will be organized with the following affiliated conferences and symposia:

CLOUD: IEEE International Conference on Cloud Computing
The flagship theme-topic conference for modeling, developing, publishing, monitoring, managing, delivering XaaS (everything as a service) in the context of various types of cloud environments.

ICWS: IEEE International Conference on Web Services
The flagship theme-topic conference for Web-based services, featuring Web services modeling, development, publishing, discovery, composition, testing, adaptation, and delivery, and Web services technologies as well as standards.

SCC: IEEE International Conference on Services Computing
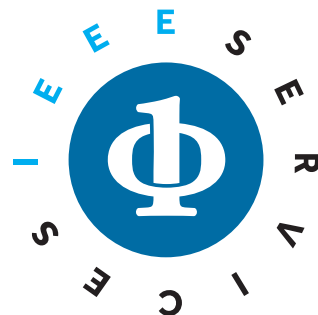The flagship theme-topic conference for services innovation lifecycle that includes enterprise and vertical services modeling, microservices based solution creation, services orchestration, services optimization, services management, services marketing, and business process integration and management.

SMDS: IEEE International Conference on Smart Data Services
The flagship theme-topic conference for data driven applications and solutions under the as-a-service model, including analytic services, smart data foundation, big data services, blockchain, and data computing at the edge and in IoT systems.

DHAASS: Symposium on Digital Health as a Service
DHAASS represents an emerging and critical direction for SERVICES covering the application of digital health as a service in transforming health and social care. Key themes for 2020 include definitions and safe implementations of health/medical microservices (dubbed the Uber of digital health), crowd sensing/sourcing, microservice integration, health service economics, among others.

Congress Organizers

Steering Committee Chair
Carl K. Chang
Iowa State University

Congress General Chairs
Elisa Bertino
Purdue University

Hong Mei
Peking University

Program Chairs-in-Chief
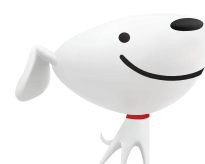Ernesto Damiani
University of Milan

Zhi Jin
Peking University

Industry Sponsors

Alibaba Group 阿里巴巴集团

Baidu 百度

HUAWEI

JD.COM